

TOSHIBA Bipolar Linear IC Silicon Monolithic

TA2131FLG

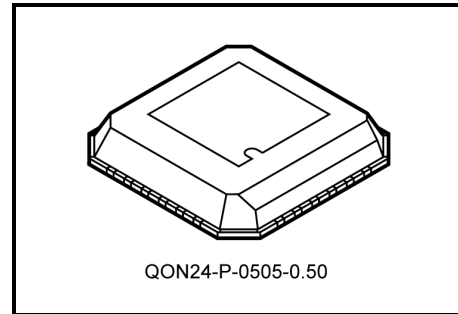
Low Current Consumption Headphone Amplifier for Portable MD Player (With Bass Boost Function)

The TA2131FLG is a low current consumption headphone amplifier developed for portable digital audio. It is particularly well suited to portable MD players that are driven by a single dry cell. It also features a built-in bass boost function with AGC, and is capable of bass amplification of DAC output and analog signals such as tuner.

An ultra-compact QON package is utilized, enabling sets to be compacted.

Features

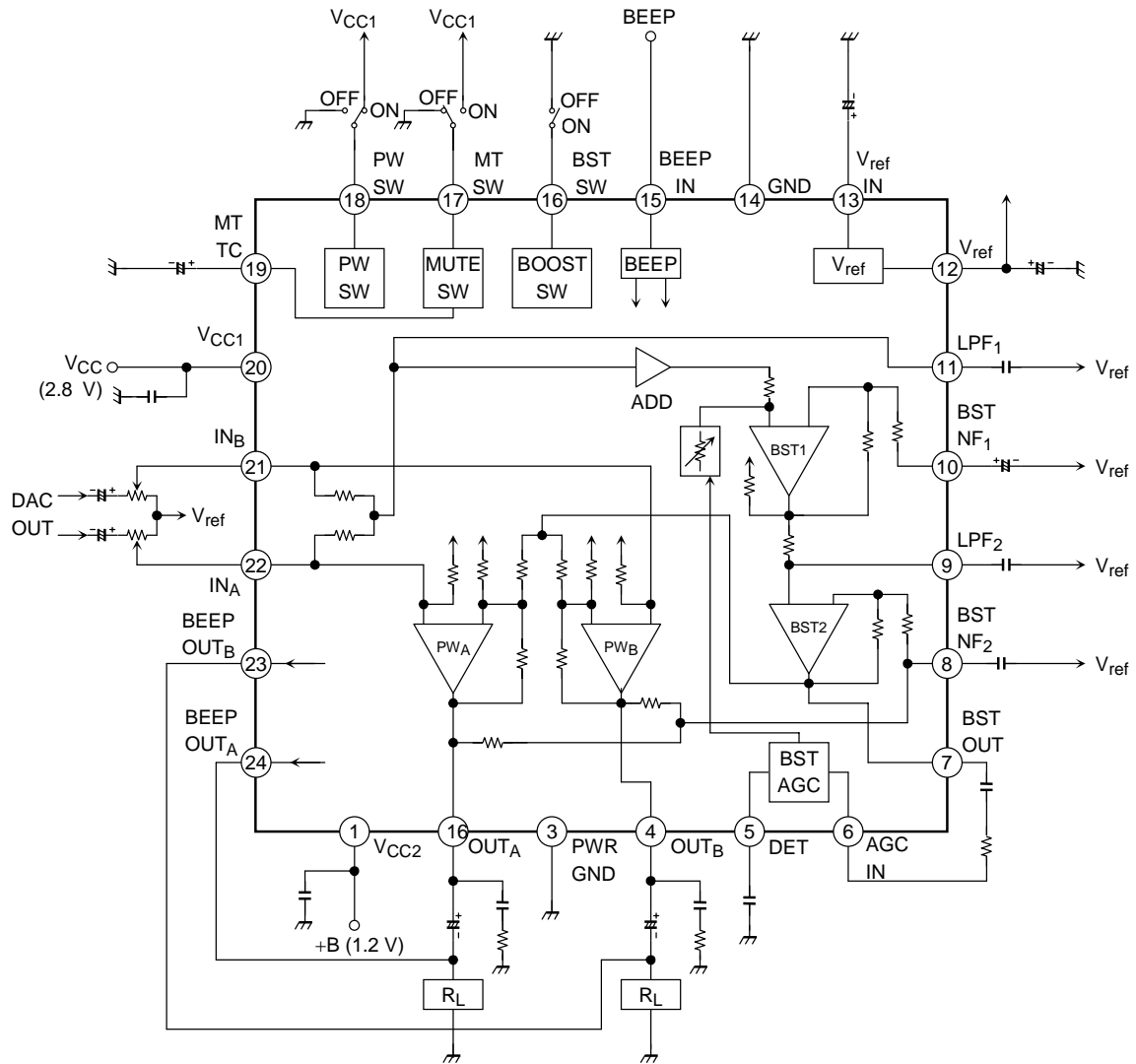
- Low current consumption: $ICCQ(VCC1) = 0.55 \text{ mA (typ.)}$
 $ICCQ(VCC2) = 0.20 \text{ mA (typ.)}$
- Output power: $P_o = 8 \text{ mW (typ.)}$
($VCC1 = 2.8 \text{ V}$, $VCC2 = 1.2 \text{ V}$, $f = 1 \text{ kHz}$, $THD = 10\%$, $R_L = 16 \Omega$)
- Low noise: $V_{no} = -102\text{dBV (typ.)}$
- Built-in low-pass boost (with AGC)
- I/O pin for beep sound
- Outstanding ripple rejection ratio
- Built-in power mute
- Built-in power ON/OFF switch
- Operating supply voltage range ($T_a = 25^\circ\text{C}$): $VCC1 = 1.8\sim 4.5 \text{ V}$
 $VCC2 = 0.9\sim 4.5 \text{ V}$



Weight: 0.05 g (typ.)

Actual product display name: 2131

Block Diagram



Terminal Explanation (Terminal voltage: Typical terminal voltage at no signal with test circuit, $V_{CC1} = 2.8\text{ V}$, $V_{CC2} = 1.2\text{ V}$, $T_a = 25^\circ\text{C}$)

Terminal No.	Terminal Explanation	Internal Circuit	Terminal Voltage (V)
1	V_{CC2}	—	1.2
2	OUT_A		0.61
4	OUT_B		0.61
21	IN_B		0.61
22	IN_A		0.61
7	BST OUT		0.61
8	BST NF ₂	BST amplifier 2 NF terminal (low-pass compensation condenser connection terminal)	0.61
3	PWR GND	—	0
5	DET		—

Terminal No.	Terminal Explanation	Internal Circuit	Terminal Voltage (V)
6	AGC IN Signal input level to BST amplifier is varied according to the input level to the boost AGC input terminal. Input impedance: 15 kΩ (typ.)		0.61
9	LPF ₂ BST amplifier 1 output (filter terminal)		0.61
10	BST NF ₁ BST amplifier 1 NF		0.61
11	LPF ₁ ADD amplifier output (filter terminal)		0.61
12	V _{ref} Reference voltage circuit		0.61
13	V _{ref} IN Reference voltage circuit filter terminal		0.61
14	GND GND of input stage in power amplifier	—	0

Terminal No.		Terminal Explanation	Internal Circuit	Terminal Voltage (V)	
15	BEEP IN	Beep sound input terminal Receives beep sound signals from microcomputer.		0	
23	BEEP OUT _B	Beep sound output terminal			—
24	BEEP OUT _A				—
16	BST SW	Bass boost ON/OFF switch "H" level/OPEN: BST ON "L" level: BST OFF Refer to function explanation 5		—	
17	MT SW	Mute switch "L" level: Mute reset "H" level: Mute ON Refer to function explanation 5		—	
18	PW SW	Power ON/OFF switch "H" level: IC operation "L" level: IC OFF Refer to function explanation 5		—	

Terminal No.		Terminal Explanation	Internal Circuit	Terminal Voltage (V)
19	MT TC	Mute smoothing Power mute switch Reduces the shock noise during switching		1.2
20	V _{CC1}	Main V _{CC}	—	2.8

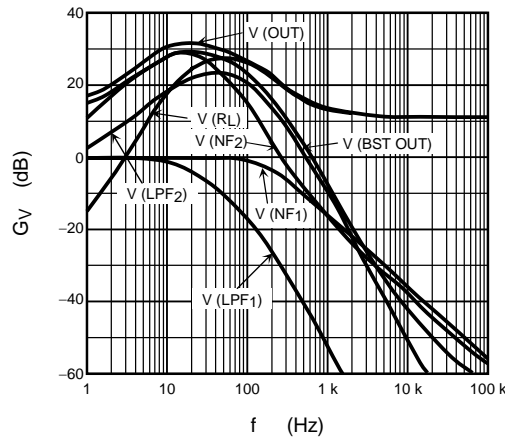


Figure 2 During Bass Boost (Frequency Characteristics to Each Terminal)

2. Low-Pass Compensation

2-1. Function

In C-couple type power amplifiers, it is necessary to give the output capacitor C a large capacity to flatten out the frequency characteristics to the low frequency band (this is because the loss in the low frequency bandwidth becomes larger due to the effect of the high-pass filter comprising C and R_L). Particularly when the headphone load is approximately 16Ω and an attempt is being made to achieve frequency characteristics of $\pm 3 \text{ dB}$ at 20 Hz, a large capacity condenser of $C = 470 \mu\text{F}$ is required.

Bearing this situation in mind, a low-pass compensation function was built in to the TA2131FLG, and while reducing the capacity of the output coupling condenser, almost flat ($\pm 3 \text{ dB}$) frequency characteristics in all audible bandwidths (20 Hz to 20 kHz) have been achieved.

Fig.3 shows the low-pass system diagram, and Fig.4 shows the frequency characteristics at each point. In Fig.4, (a) represents the status lost by the low-pass as a result of the high-pass filter comprising the headphone load ($R_L = 16 \Omega$) and the output coupling condenser ($220 \mu\text{F}$) in the C-coupling system.

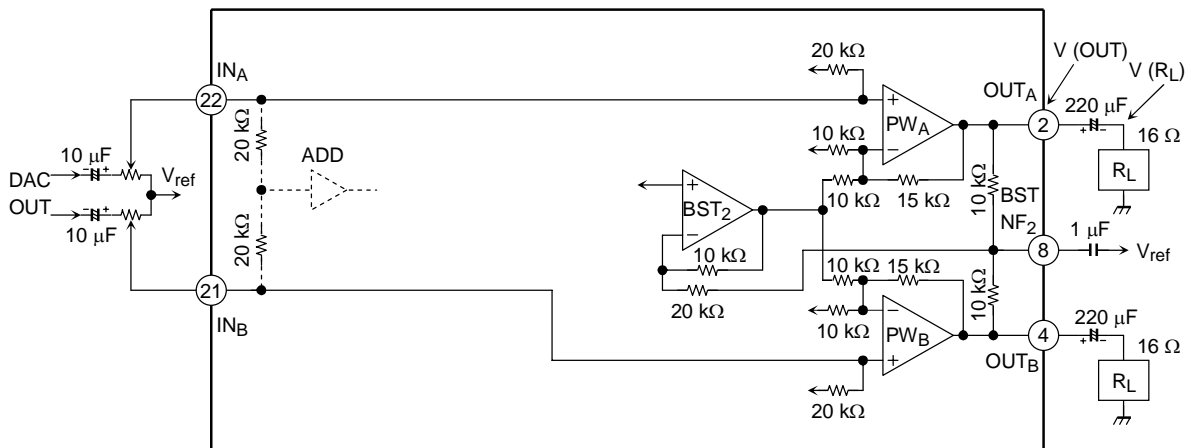


Figure 3 Low-Pass Compensation System Diagram

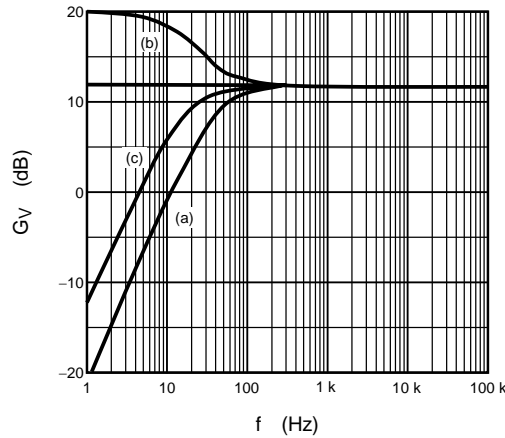


Figure 4 Power Amplifier Frequency Characteristics

<Principle of Low-Pass Compensation>

The low-pass component alone is extracted from the composite signal of PWA/PWB output, and that frequency signal is fed back to PWA/PWB once more via the inversion amplifier, thereby making it possible to increase the gain only of the low-pass component. The frequency characteristics of the power amplifier output V (OUT) in this state are shown in Fig.4 (b). In practice they are the frequency characteristics (c) viewed from load terminal V (RL), and the low-pass is compensated relative to the state in (a).

2-2. Low-Pass Compensation Condenser and Crosstalk

In this low-pass compensation condenser circuit, processing is carried out using the composite signal of power amplifier output, so this affects crosstalk, according to the amount of compensation. f characteristics and crosstalk generated by the capacity of the condenser for compensation (8-pin) are shown below.

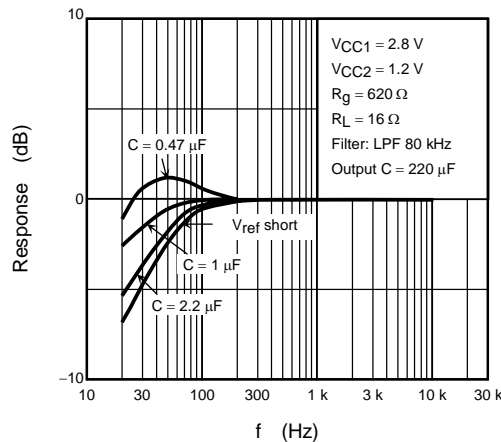


Figure 5 Condenser and f Characteristics for Low-Pass Compensation

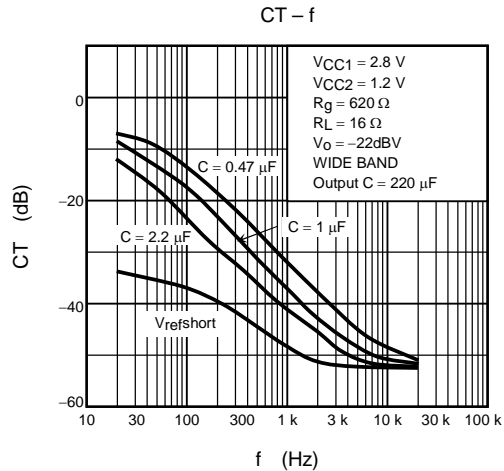
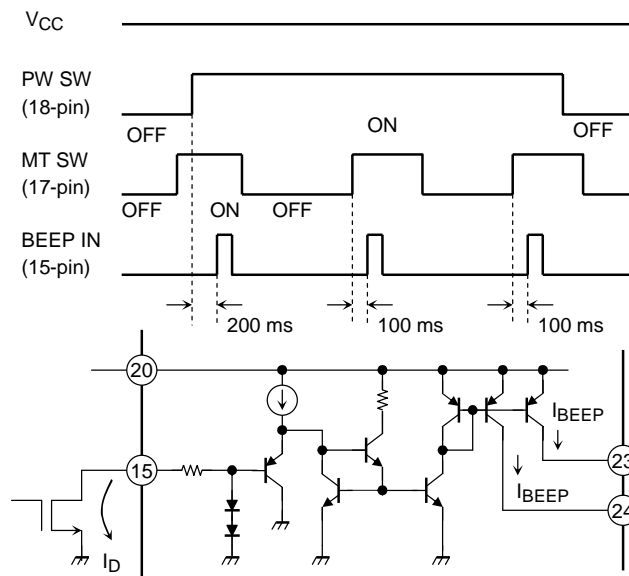


Figure 6 Low-Pass Compensation Condenser and Crosstalk

3. Beep

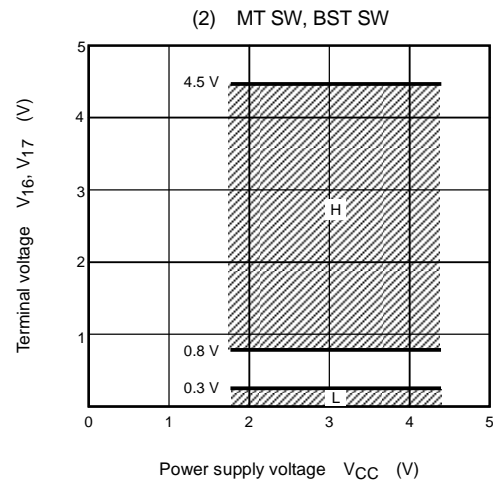
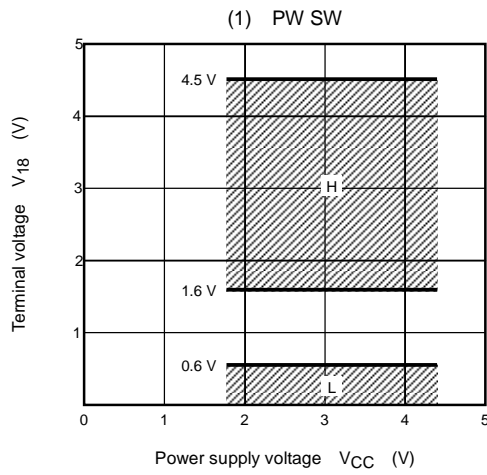
Beep sound signals from microcomputer can be received by the beep input terminal (15-pin). The PWA and PWB of the power amplifier during power mute are turned OFF, and the beep signal input from BEEP-IN (15-pin) is output from the BEEP-OUT terminal (23/24-pin) as fixed current, after passing through the converter and current amplification stage. Connecting this terminal to the headphone load outputs the beep sound. If the beep sound is not input, fix the BEEP-IN (15-pin) terminal to GND level.



4. Power Switch

As long as the power switch is not connected to “H” level, the IC does not operate. If it malfunctions due to external noise, however, it is recommended to connect a pull-down resistor externally (the power switch is set to be highly sensitive).

5. Threshold Voltages of Switches



	PW SW (V_{18})
"H" level	IC operation
"L" level	IC OFF

	MT SW (V_{17})
"H" level	Mute ON
"L" level	Mute reset

	BST SW (V_{16})
"H" level/OPEN	BST ON
"L" level	BST OFF

6. These capacitors which prevent oscillation of the power amplifier, and are between the V_{ref} and V_{CC-GND} must have a small temperature coefficient and outstanding frequency characteristics.

Absolute Maximum Ratings

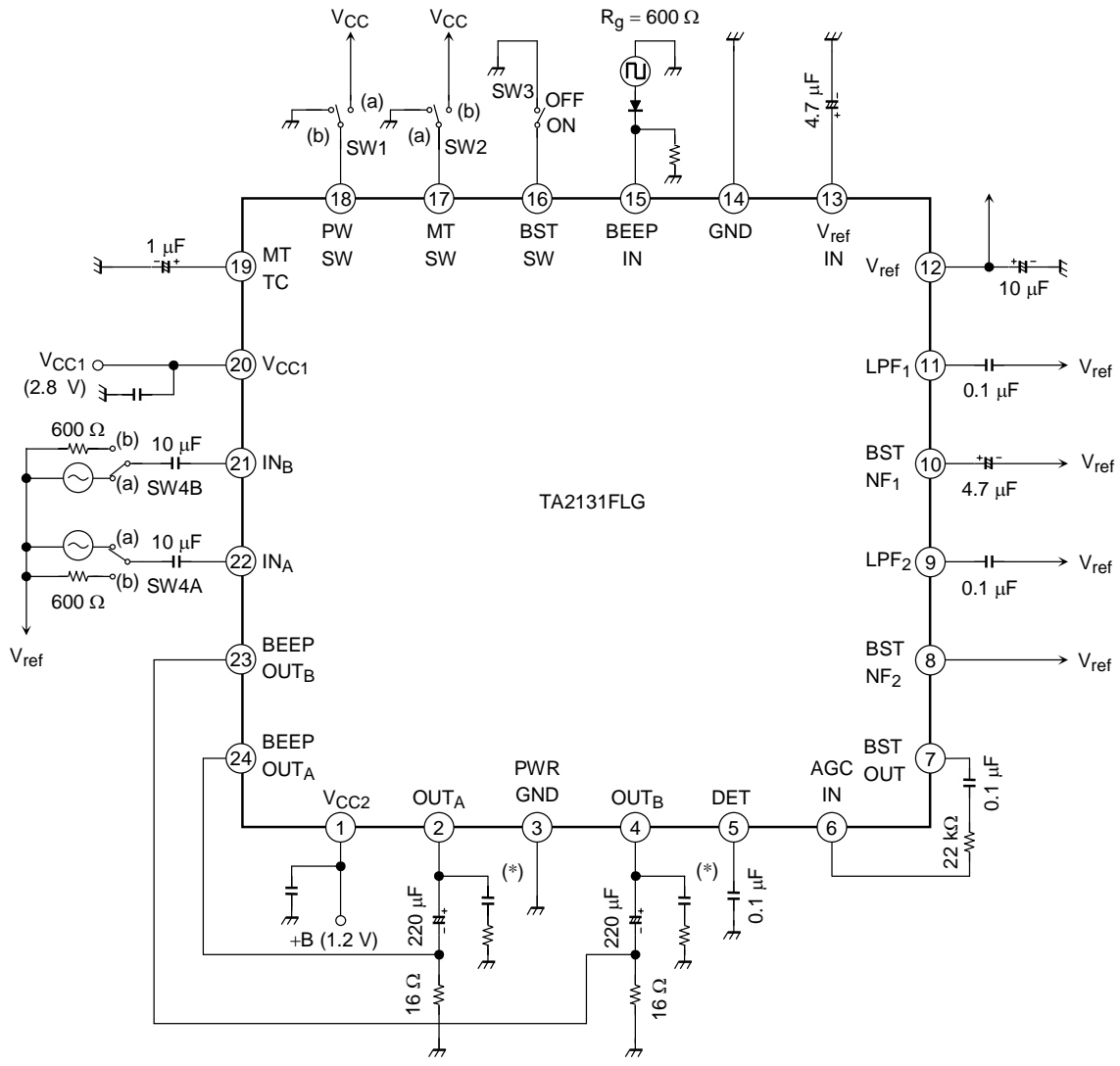
Characteristic	Symbol	Rating	Unit
Supply voltage	V_{CC}	4.5	V
Output current	I_o (peak)	100	mA
Power dissipation	P_D (Note)	350	mW
Operating temperature	T_{opr}	-25~75	°C
Storage temperature	T_{stg}	-55~150	°C

Note: Derated above $T_a = 25^\circ\text{C}$ in the proportion of 2.8 mW/°C.

Electrical Characteristics (Unless specified otherwise, $V_{CC1} = 2.8\text{ V}$, $V_{CC2} = 1.2\text{ V}$, $R_g = 600\ \Omega$, $R_L = 16\ \Omega$, $f = 1\text{ kHz}$, $T_a = 25^\circ\text{C}$)

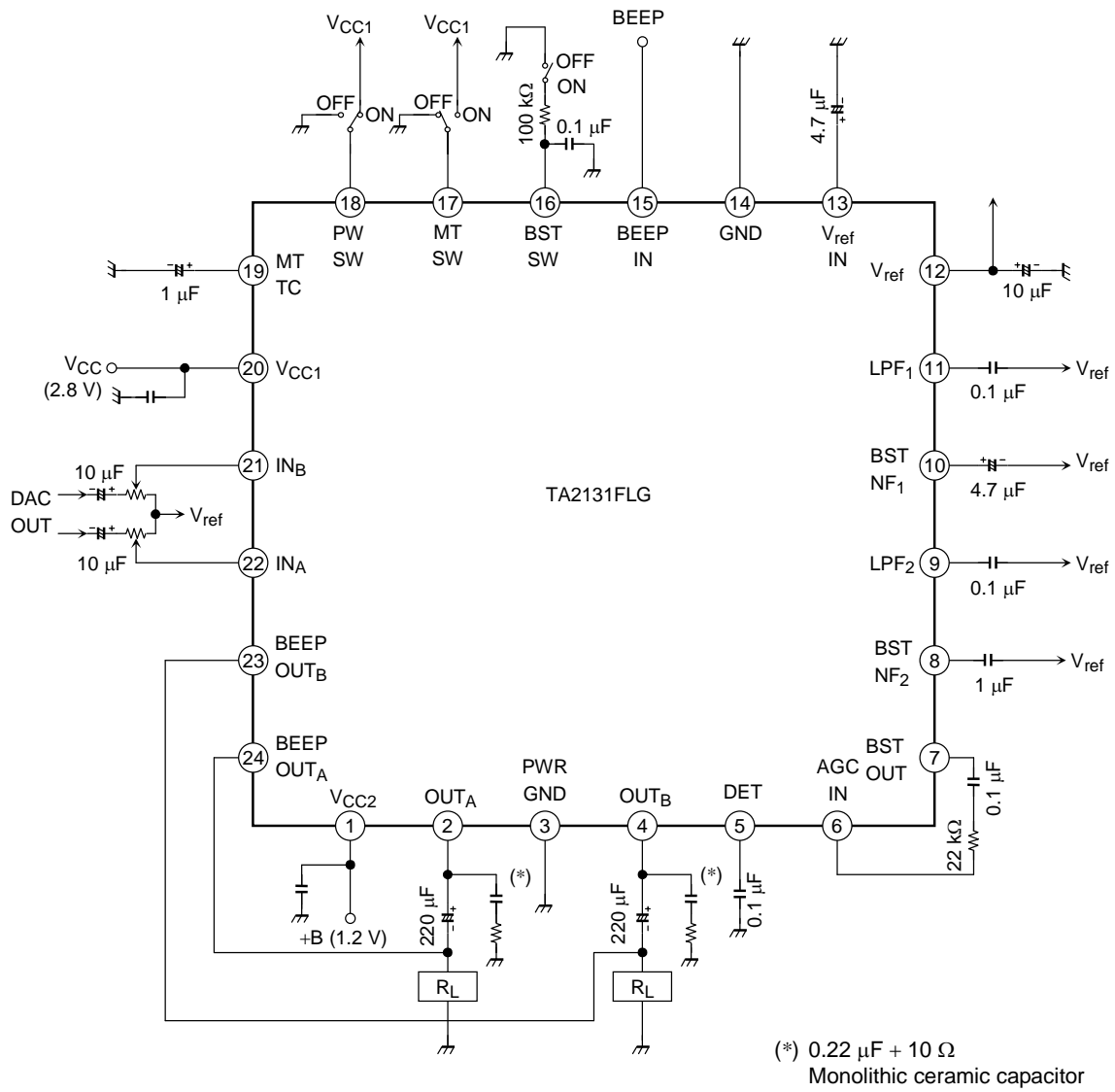
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit	
Quiescent supply current		I_{CC1}	IC off (V_{CC1}), SW1: b, SW2: b	—	0.1	5	μA	
		I_{CC2}	IC off (V_{CC2}), SW1: b, SW2: b	—	0.1	5		
		I_{CC3}	Mute on (V_{CC1}), SW1: a, SW2: b	—	0.35	0.50	mA	
		I_{CC4}	Mute on (V_{CC2}), SW1: a, SW2: b	—	5	10	μA	
		I_{CC5}	No signal (V_{CC1}), SW1: a, SW2: a	—	0.55	0.75	mA	
		I_{CC6}	No signal (V_{CC2}), SW1: a, SW2: a	—	0.20	0.40		
	Power supply current during drive		I_{CC7}	$P_o = 0.5\text{ mW} + 0.5\text{ mW output}$ (V_{CC1})	—	0.6	—	mA
			I_{CC8}	$P_o = 0.5\text{ mW} + 0.5\text{ mW output}$ (V_{CC2})	—	5.3	—	
Power Section	Gain	G_V	$V_o = -22\text{dBV}$	10	12	14	dB	
	Channel balance	CB	$V_o = -22\text{dBV}$	-1.5	0	1.5		
	Output power	$P_o\text{ max}$	THD = 10%	5	8	—	mW	
	Total harmonic distortion	THD	$P_o = 1\text{ mW}$	—	0.1	0.3	%	
	Output noise voltage	V_{no}	$R_g = 600\ \Omega$, Filter: IHF-A, SW4: b	—	-102	-96	dBV	
	Crosstalk	CT	$V_o = -22\text{dBV}$	-42	-48	—		
	Ripple rejection ratio	RR1	$f_r = 100\text{ Hz}$, $V_r = -20\text{dBV}$ inflow to V_{CC2}	-71	-77	—	dB	
		RR2	$f_r = 100\text{ Hz}$, $V_r = -20\text{dBV}$ inflow to V_{CC1}	-54	-64	—		
	Mute attenuation	ATT	$V_o = -12\text{dBV}$, SW2: a \rightarrow b	-90	-100	—	dBV	
Beep sound output voltage	VBEEP	V Beep IN = $2 V_{p-o}$, SW2: b	-53	-48	-43			
Boost gain	BST1	$V_o = -20\text{dBV}$, $f = 100\text{ Hz}$, SW3: ON \rightarrow OPEN	1	4	7	dB		
	BST2	$V_o = -30\text{dBV}$, $f = 100\text{ Hz}$, SW3: ON \rightarrow OPEN	10	13	16			
	BST3	$V_o = -50\text{dBV}$, $f = 100\text{ Hz}$, SW3: ON \rightarrow OPEN	13.5	16.5	19.5			

Test Circuit

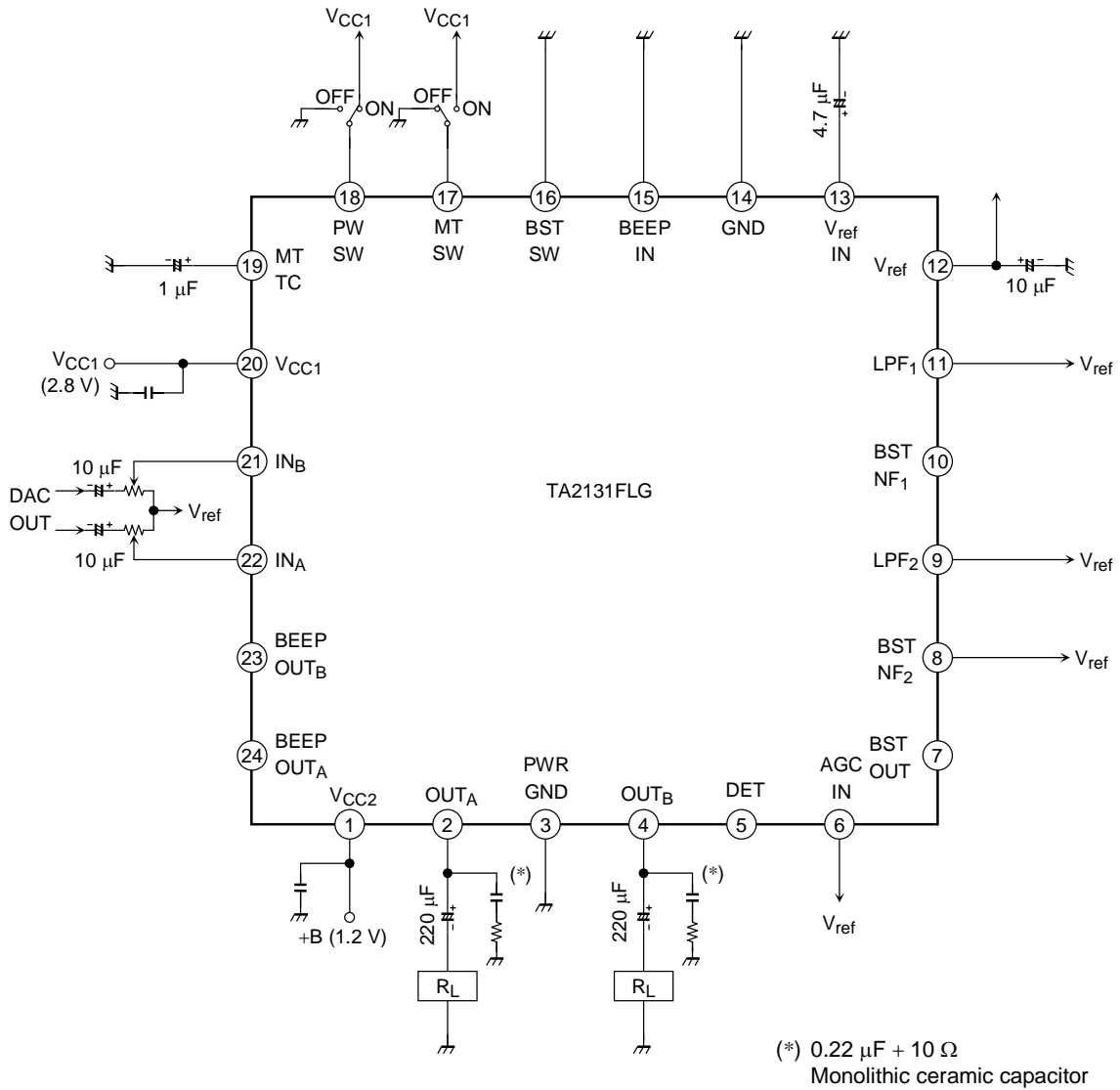


(*) 0.22 μF + 10 Ω
Monolithic ceramic capacitor

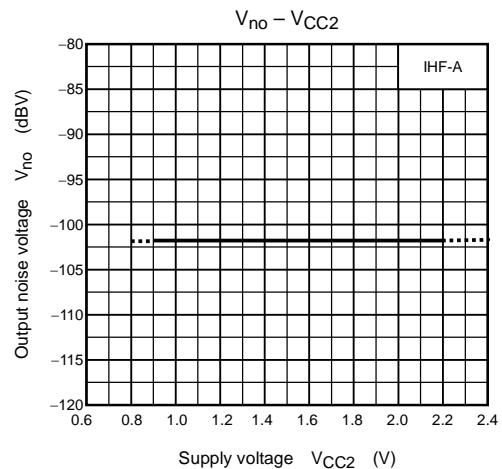
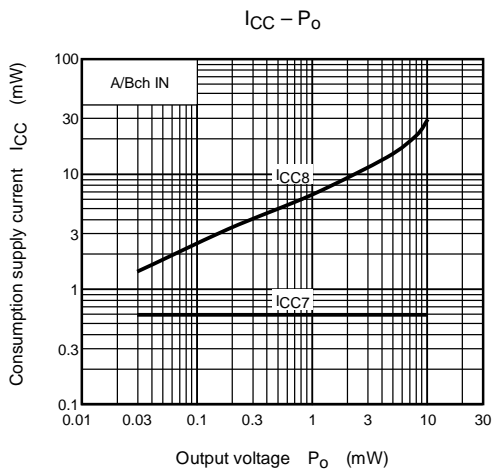
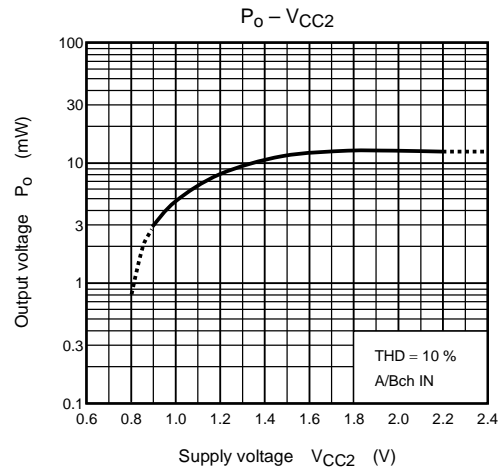
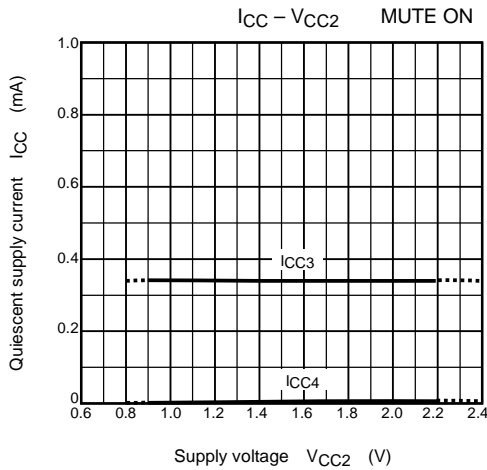
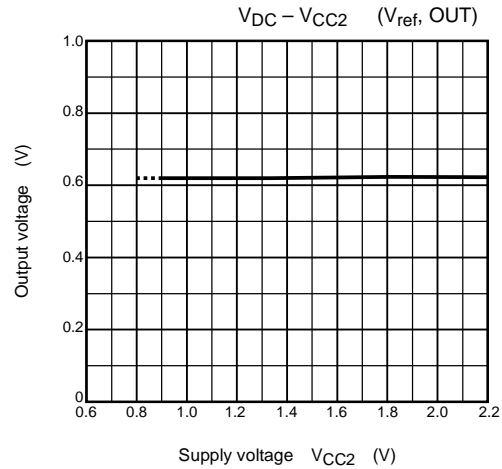
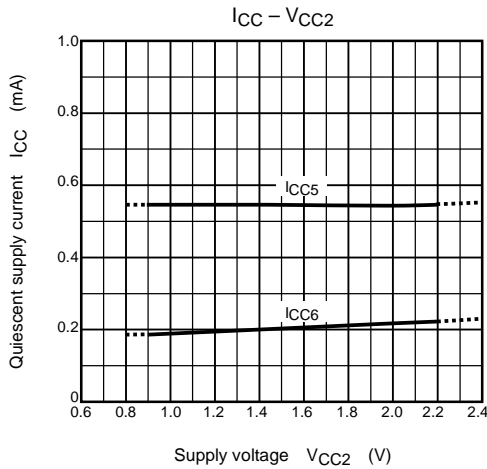
Application Circuit 1

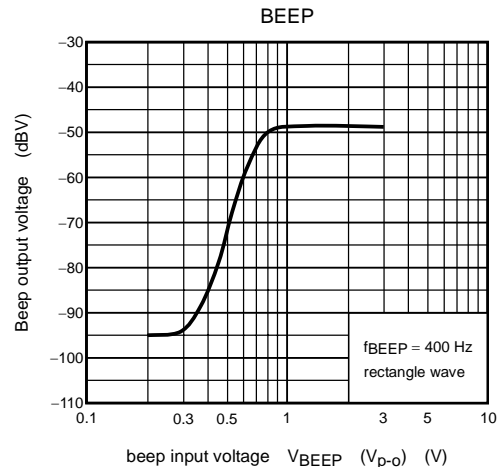
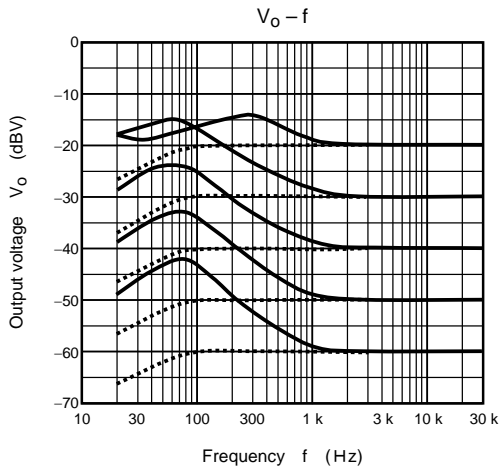
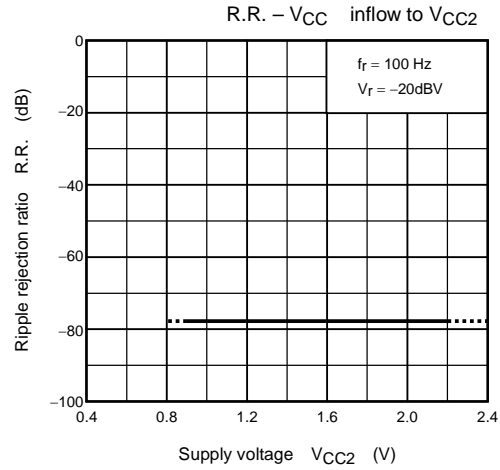
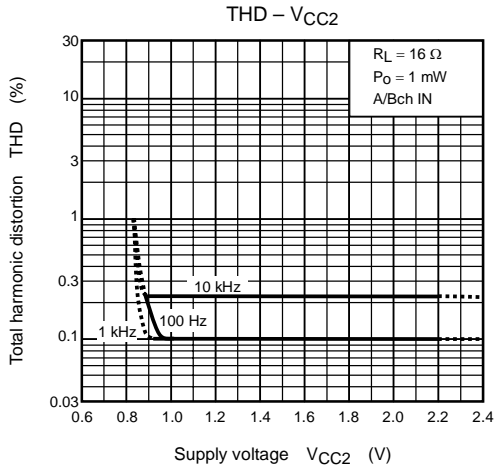
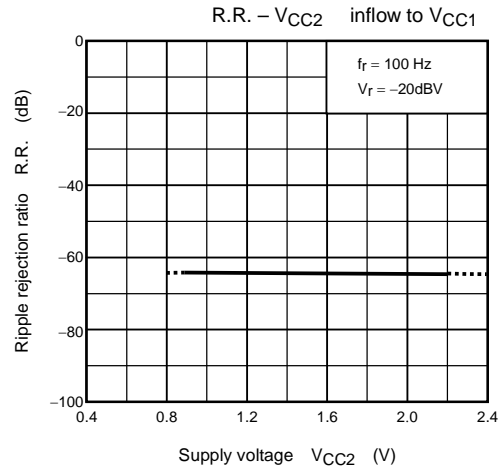
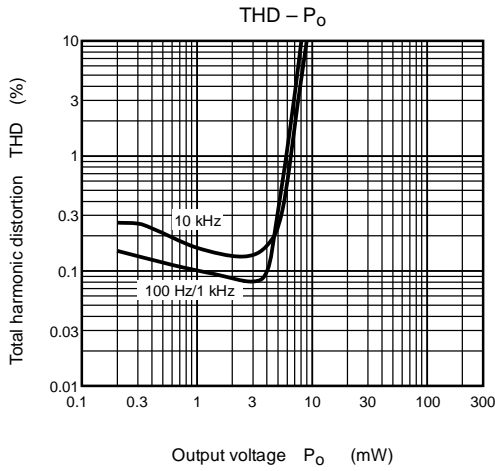


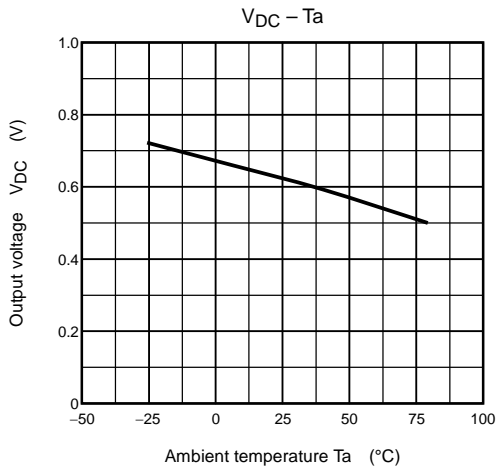
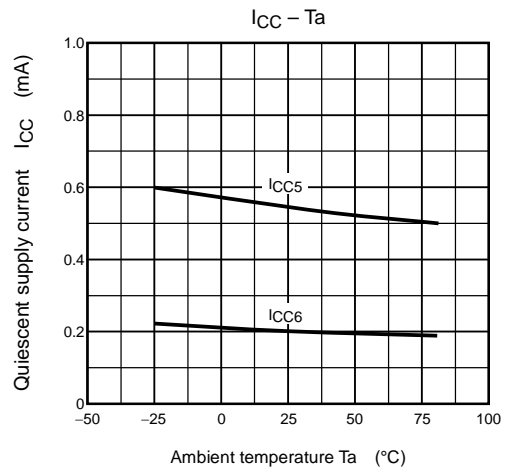
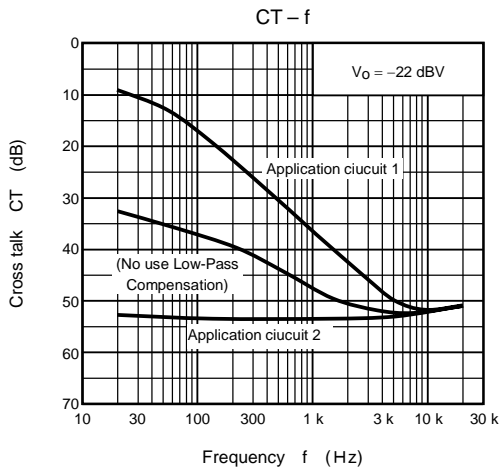
Application Circuit 2 (Low-Pass Compensation/Bass Boost Function/BEEP Not Used)



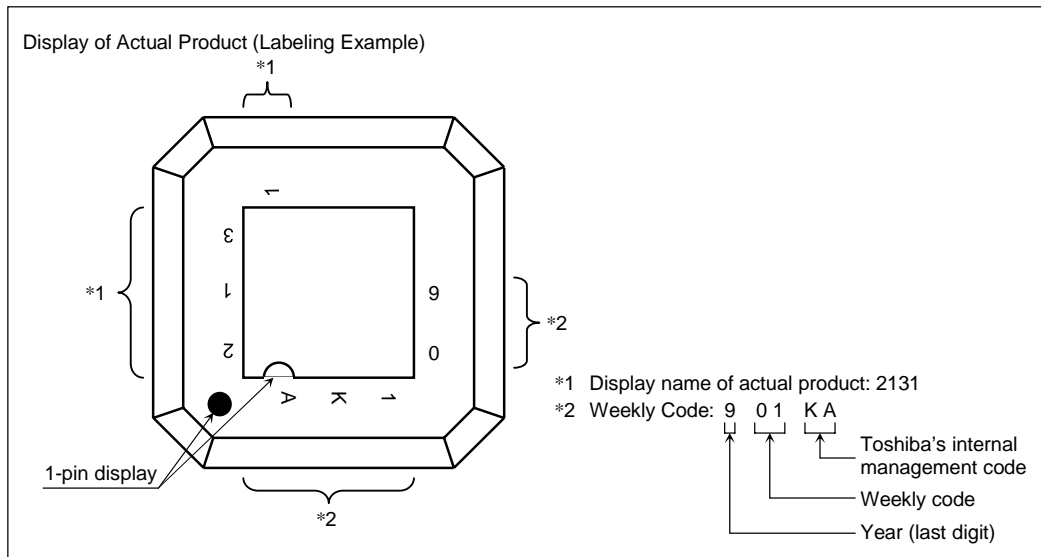
Characteristics (Unless otherwise specified $V_{CC1} = 2.8\text{ V}$, $V_{CC2} = 1.2\text{ V}$, $R_g = 600\ \Omega$, $f = 1\text{ kHz}$, $T_a = 25^\circ\text{C}$)





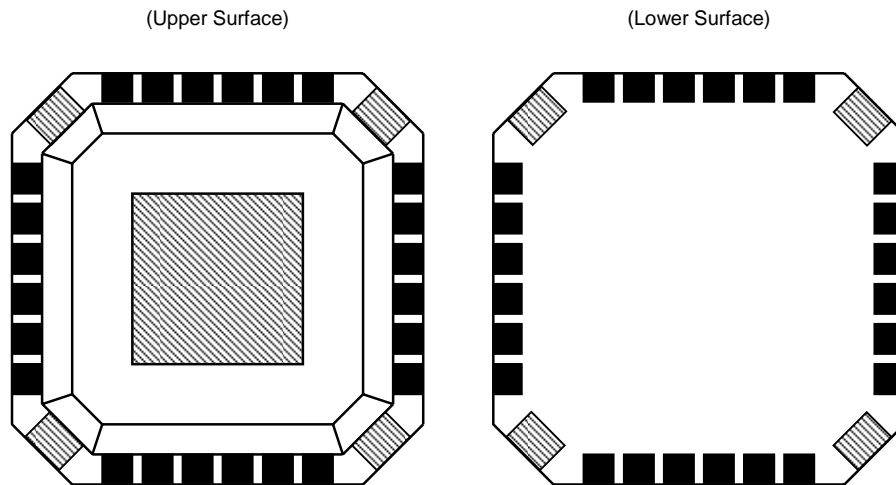


Display of Actual Product



Requests Concerning Use of QON

Outline Drawing of Package



When using QON, please take into account the following items.

- (1) Do not carry out soldering on the island section in the four corners of the package (the section shown on the lower surface drawing with diagonal lines) with the aim of increasing mechanical strength.
- (2) The island section exposed on the package surface (the section shown on the upper surface drawing with diagonal lines) must be used as *1 below while electrically insulated from outside.

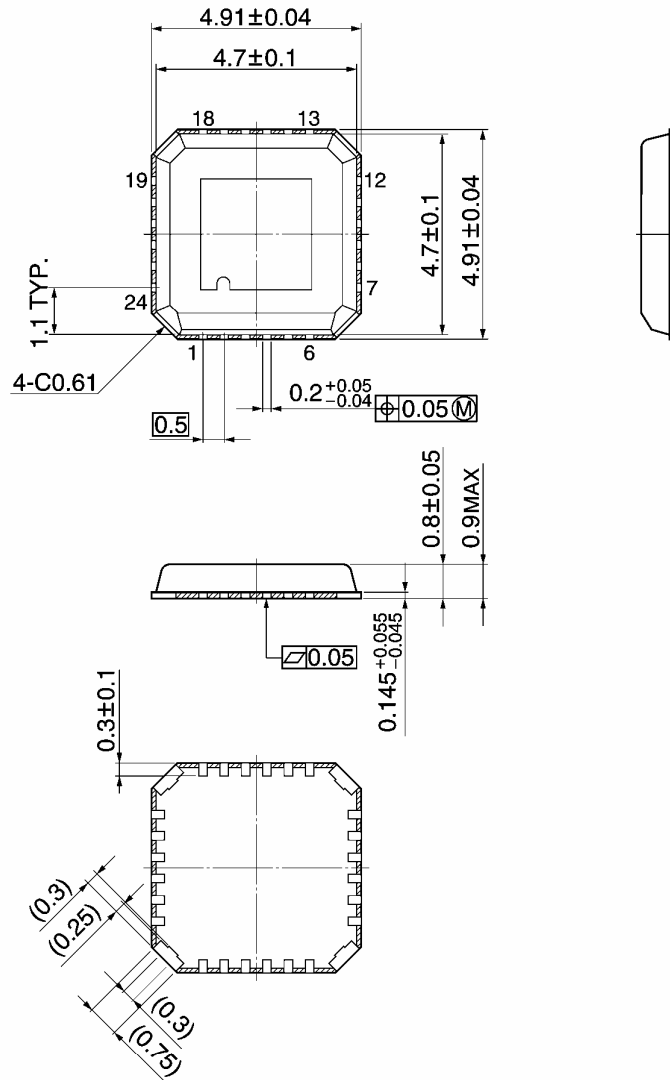
Note 1: Ensure that the island section (the section shown on the lower surface drawing with diagonal lines) does not come into contact with solder from through-holes on the board layout.

- When mounting or soldering, take care to ensure that neither static electricity nor electrical overstress is applied to the IC (measures to prevent anti-static, leaks, etc.).
- When incorporating into a set, adopt a set design that does not apply voltage directly to the island section.

Package Dimensions

QON24-P-0505-0.50

Unit: mm



Note 1) The solder plating portion in four corners of the package shall not be treated as an external terminal.

Note 2) Don't carry out soldering to four corners of the package.

Note 3)  area : Resin surface

Weight: 0.05 g (typ.)

RESTRICTIONS ON PRODUCT USE

060116EBA

- The information contained herein is subject to change without notice. 021023_D
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
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- The products described in this document are subject to the foreign exchange and foreign trade laws. 021023_E

About solderability, following conditions were confirmed

- Solderability
 - (1) Use of Sn-37Pb solder Bath
 - solder bath temperature = 230°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux
 - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
 - solder bath temperature = 245°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux